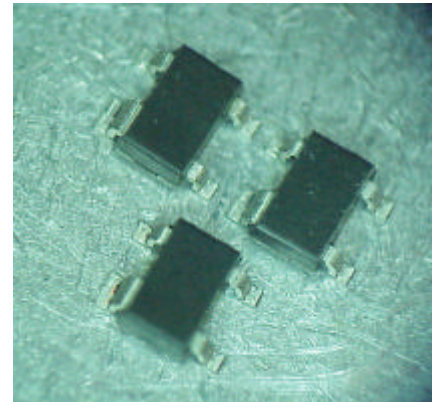


FEATURES

- ◆ 0.6 dB Noise Figure at 2 GHz
- ◆ 15.5 dBm P-1dB 2 GHz, 16.5 dBm at 6 GHz
- ◆ 21 dB Power Gain at 2 GHz, 10.5 dB at 6GHz
- ◆ 50% Power-Added-Efficiency at 2 GHz


DESCRIPTION AND APPLICATIONS

The LPD200 is an Aluminum Gallium Arsenide / Indium Gallium Arsenide (AlGaAs/InGaAs) Pseudomorphic High Electron Mobility Transistor (PHEMT), utilizing an Electron-Beam direct-write 0.25 μm by 200 μm Schottky barrier gate. The recessed “mushroom” Ti/Pt/Au gate structure minimizes parasitic gate-source and gate resistances. The epitaxial structure and processing have been optimized for high dynamic range. The LPD200’s active areas are passivated with Si_3N_4 , and the SOT343 (also known as SC-70) package is ideal for low-cost, high-performance applications that require a surface-mount package.

The LPD200SOT343 is designed for commercial systems for use in low noise amplifiers and oscillators operating over the RF and Microwave frequency ranges. The low noise figure makes it appropriate for use in receivers in MMDS and GPS. This device is also suitable as a driver stage for WLAN and ISM band spread spectrum applications.

ELECTRICAL SPECIFICATIONS @ $T_{\text{Ambient}} = 25^\circ\text{C}$

| Parameter | Symbol | Test Conditions | Min | Typ | Max | Units |
|---|---------------------|---|-------|------|------|---------------|
| Saturated Drain-Source Current | I_{DSS} | $V_{\text{DS}} = 2 \text{ V}; V_{\text{GS}} = 0 \text{ V}$ | 45 | | 75 | mA |
| Power at 1-dB Compression | P-1dB | $f=2\text{GHz}; V_{\text{DS}} = 3 \text{ V}; I_{\text{DS}} = 50\% I_{\text{DSS}}$ | 14 | 15.5 | | dBm |
| Power Gain at 1-dB Compression | G-1dB | $f=2\text{GHz}; V_{\text{DS}} = 3 \text{ V}; I_{\text{DS}} = 50\% I_{\text{DSS}}$ | 20 | 21 | | dB |
| Power-Added Efficiency | PAE | $f=2\text{GHz}; V_{\text{DS}} = 3 \text{ V}; I_{\text{DS}} = 50\% I_{\text{DSS}};$ $P_{\text{OUT}} = 19.5 \text{ dBm}$ | | 50 | | % |
| Noise Figure | NF | $f=2\text{GHz}; V_{\text{DS}} = 3\text{V}; I_{\text{DS}} = 25\% I_{\text{DSS}}$ | | 0.6 | | dB |
| | | $f=2\text{GHz}; V_{\text{DS}} = 5\text{V}; I_{\text{DS}} = 50\% I_{\text{DSS}}$ | | 0.8 | | dB |
| Transconductance | G_{M} | $V_{\text{DS}} = 2 \text{ V}; V_{\text{GS}} = 0 \text{ V}$ | 50 | 70 | | mS |
| Gate-Source Leakage Current | I_{GSO} | $V_{\text{GS}} = -5 \text{ V}$ | | 1 | 10 | μA |
| Pinch-Off Voltage | V_{P} | $V_{\text{DS}} = 2 \text{ V}; I_{\text{DS}} = 1 \text{ mA}$ | -0.25 | | -1.5 | V |
| Gate-Source Breakdown Voltage Magnitude | $ V_{\text{BDGS}} $ | $I_{\text{GS}} = 1 \text{ mA}$ | 6 | 7 | | V |
| Gate-Drain Breakdown Voltage Magnitude | $ V_{\text{BDGD}} $ | $I_{\text{GD}} = 1 \text{ mA}$ | 8 | 9 | | V |

• ABSOLUTE MAXIMUM RATINGS

| Parameter | Symbol | Test Conditions | Min | Max | Units |
|-------------------------------|-----------|---|-----|-----------|------------------|
| Drain-Source Voltage | V_{DS} | $T_{Ambient} = 22 \pm 3 \text{ }^\circ\text{C}$ | | 7 | V |
| Gate-Source Voltage | V_{GS} | $T_{Ambient} = 22 \pm 3 \text{ }^\circ\text{C}$ | | -3 | V |
| Drain-Source Current | I_{DS} | $T_{Ambient} = 22 \pm 3 \text{ }^\circ\text{C}$ | | I_{DSS} | mA |
| Gate Current | I_G | $T_{Ambient} = 22 \pm 3 \text{ }^\circ\text{C}$ | | 5 | mA |
| RF Input Power | P_{IN} | $T_{Ambient} = 22 \pm 3 \text{ }^\circ\text{C}$ | | 60 | mW |
| Channel Operating Temperature | T_{CH} | $T_{Ambient} = 22 \pm 3 \text{ }^\circ\text{C}$ | | 175 | $^\circ\text{C}$ |
| Storage Temperature | T_{STG} | — | -65 | 175 | $^\circ\text{C}$ |

Notes: Even temporary operating conditions that exceed the Absolute Maximum Ratings could result in permanent damage to the device.

• HANDLING PRECAUTIONS

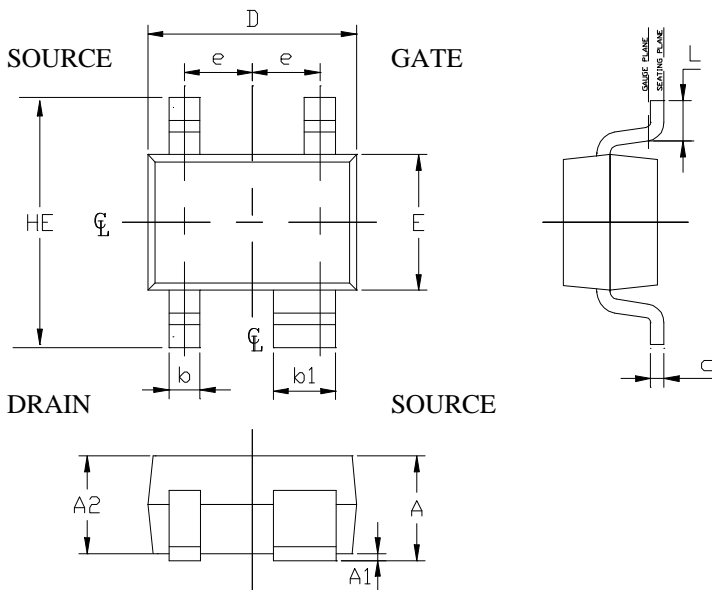
To avoid damage to the devices care should be exercised during handling. Proper Electrostatic Discharge (ESD) precautions should be observed at all stages of storage, handling, assembly, and testing. These devices should be treated as Class 1A (0-500 V). Further information on ESD control measures can be found in MIL-STD-1686 and MIL-HDBK-263.

• APPLICATIONS NOTES & DESIGN DATA

Applications Notes are available from your local Filtronic Sales Representative or directly from the factory. Complete design data, including S-parameters, noise data, and large-signal models are available on the Filtronic web site.

• PACKAGE OUTLINE

(dimensions in mm)



| SYMBOL | MIN | MAX |
|--------|----------|------|
| E | 1.15 | 1.35 |
| D | 1.85 | 2.25 |
| HE | 1.80 | 2.40 |
| A | 0.80 | 1.10 |
| A2 | 0.80 | 1.00 |
| A1 | 0.00 | 0.10 |
| e | 0.65 BSC | |
| b | 0.25 | 0.40 |
| b1 | 0.55 | 0.70 |
| c | 0.10 | 0.18 |
| L | 0.26 | 0.46 |

All information and specifications are subject to change without notice.